

TECHNICAL DATA SHEET Description: 13.56MHz RFID/NFC SMD Antenna

Series: Embedded NFC

PART NUMBER: W3102

Features:

- Antenna type coil on ferrite core
- Frequency 13.56MHz
- Inductance 4.7uH
- Read Distance 17mm
- Size 7.8 x 7 x 5 mm
- Fully SMD compatible
- · RoHS Compliant
- MSL level 3

Applications:

- RFID / NFC systems
- · Pairing, Sharing

All dimensions are in mm / inches

Issue: 1851

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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ELECTRICAL SPECIFICATIONS

Antenna Type	coil
Frequency	13.56 MHz
Nominal Impedance	50 Ω/80Ω
Self inductance	4.7uH
resistance	0.25Ω
read distance	17mm

MECHANICAL SPECIFICATIONS

Size Weight Antenna Material 7.8 X 7.0 X 5.0 mm 0.83 g Core: 7.8 X 5.0(SH)DR B3.0 DR7.8 X 5.0 B3.0 Wire: 2UEW

ENVIRONMENTAL SPECIFICATIONS				
Operating Temperature	-40 ~ +125° C			
Storage Temperature	-20 ~ +80° C			
RoHS Compliant	Yes			

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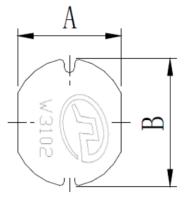


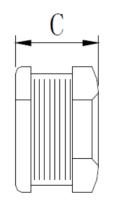
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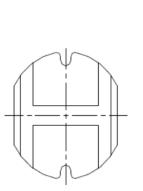
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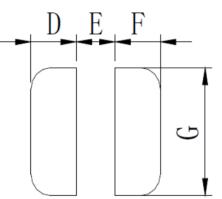
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MECHANICAL DRAWING









Recommend Solder Dimension

Dimension	А	В	С	D	Е	F	G
Unit (mm/in)	7.0±0.3/0.28±0.01	7.8±0.3/0.31±0.01	5.0±0.35/0.20±0.01	2.5/0.10 Ref	2.7/0.11 Ref	2.5/0.10 Ref	7.5/0.30 Ref

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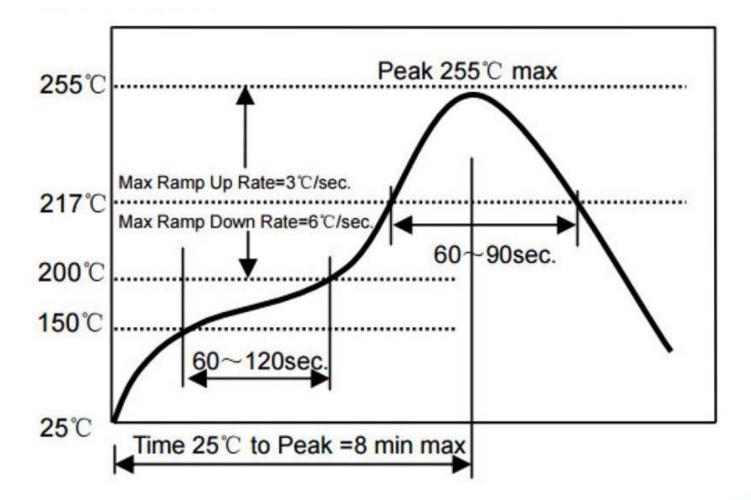
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Reflow Soldering Temperature Profile Recommendation



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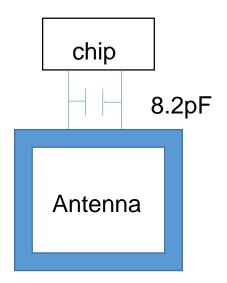
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TEST SETUP



ACR card reader



Matching circuit

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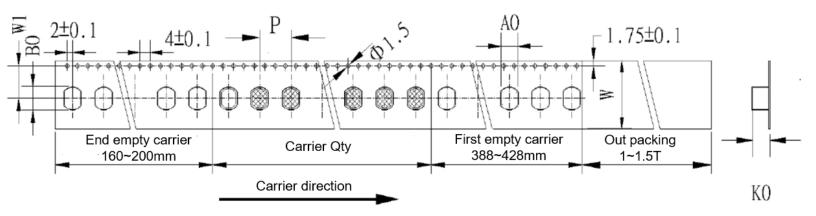
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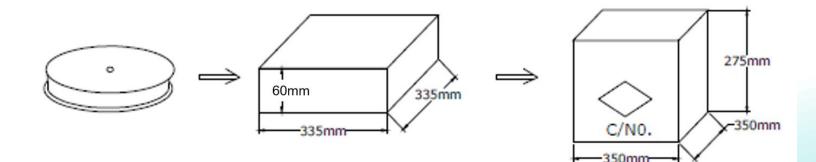
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PACKAGING

1. Tape and reel packing with plastic vacuum bag. 1000 PCS/ REEL, 3 Reels/ Small BOX, 3 Small Boxes/ Big Box



Туре			Ca	arrier Size			
	W	W1	Т	Р	AO	BO	КО
W3102	16	12.5	0.4	12	7.5	6. 1	9.5



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2. MSL: Level 3

2.1 Calculated shelf life in sealed bag: 12 months at < 30° C and 60° relative humidity (RH)

2.2 Peak temperature in reflow: 255 °C Max

2.3 After bag is opened, devices that will be subjected to reflow solder or other temperature process must:

a) Mount within: 168 hours of factory conditions \leq 30 °C/60%

b) stored at < 20% RH

2.4 Devices require bake, before mounting, if:

a) Humidity Indicator Card is > 20% when read at 23 \pm 5 °C

b) 3a or 3b not met

2.5 If baking is required, devices may be baked for 24 hours at 125~130 °C

